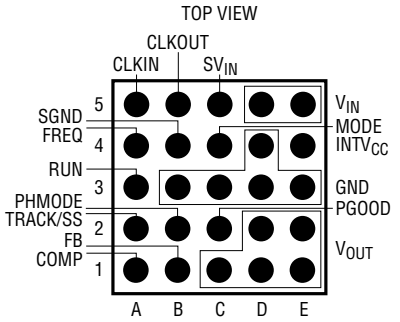
ABSOLUTE MAXIMUM RATINGS

(Note 1)

V_{IN}, SV_{IN} ..... –0.3V to 22V
V_{OUT} ..... –0.3V to SV_{IN} or 6V
RUN ..... –0.3V to 22V
$INTV_{CC}$ ..... –0.3V to 3.6V
PGOOD, MODE, TRACK/SS, FREQ,
PHMODE, CLKIN ..... –0.3V to $INTV_{CC}$
Internal Operating Junction Temperature Range
(Notes 2, 5) ..... –40°C to 125°C
Storage Temperature Range ..... –65°C to 150°C
Peak Solder Reflow Body Temperature ..... 260°C

PIN CONFIGURATION

(See Pin Functions, Pin Configuration Table)



LGA PACKAGE 25-LEAD (6.25mm × 6.25mm × 1.82mm)
BGA PACKAGE 25-LEAD (6.25mm × 6.25mm × 2.42mm)

T_{JMAX} = 125°C, θ_{JCtop} = 17°C/W, $\theta_{JCbottom}$ = 11°C/W,
$\theta_{JB} + \theta_{BA}$ = 22°C/W, θ_{JA} = 22°C/W,
θ_{JA} DERIVED FROM 95mm × 76mm PCB WITH 4 LAYERS
θ VALUES DETERMINED PER JESD51-12, WEIGHT = 0.5g

ORDER INFORMATION

PART NUMBER	PAD OR BALL FINISH	PART MARKING*		PACKAGE TYPE	MSL RATING	TEMPERATURE RANGE (Note 2)
		DEVICE	FINISH CODE			
LTM4623EV#PBF	Au (RoHS)	LTM4623V	e4	LGA	3	–40°C to 125°C
LTM4623IV#PBF	Au (RoHS)	LTM4623V	e4	LGA	3	–40°C to 125°C
LTM4623EY#PBF	SAC305 (RoHS)	LTM4623Y	e1	BGA	3	–40°C to 125°C
LTM4623IY#PBF	SAC305 (RoHS)	LTM4623Y	e1	BGA	3	–40°C to 125°C
LTM4623IY	SnPb (63/37)	LTM4623Y	e0	BGA	3	–40°C to 125°C

- Consult Marketing for parts specified with wider operating temperature ranges. *Pad or ball finish code is per IPC/JEDEC J-STD-609.
- Recommended LGA and BGA PCB Assembly and Manufacturing Procedures
- LGA and BGA Package and Tray Drawings

ELECTRICAL CHARACTERISTICS

The ● denotes the specifications which apply over the full internal operating temperature range (Note 2), otherwise specifications are at T_A = 25°C. V_{IN} = SV_{IN} = 12V per the typical application shown on the front page.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
V_{IN}	Input DC Voltage	SV_{IN} = V_{IN}	●	4		20	V
$V_{OUT(RANGE)}$	Output Voltage Range		●	0.6		5.5	V
$V_{OUT(DC)}$	Output Voltage, Total Variation with Line and Load	C_{IN} = 22µF, C_{OUT} = 100µF Ceramic, R_{FB} = 40.2k, MODE = $INTV_{CC}$, I_{OUT} = 0A to 3A (Note 3) –40°C to 125°C	 ●	 1.477	 1.50	 1.523	 V
V_{RUN}	RUN Pin On Threshold	V_{RUN} Rising		1.1	1.2	1.3	V
$I_{Q(SVIN)}$	Input Supply Bias Current	V_{IN} = 12V, V_{OUT} = 1.5V, MODE = $INTV_{CC}$ V_{IN} = 12V, V_{OUT} = 1.5V, MODE = GND Shutdown, RUN = 0, V_{IN} = 12V			6 2 11		mA mA µA
$I_{S(VIN)}$	Input Supply Current	V_{IN} = 12V, V_{OUT} = 1.5V, I_{OUT} = 3A			0.5		A
$I_{OUT(DC)}$	Output Continuous Current Range	V_{IN} = 12V, V_{OUT} = 1.5V		0		3	A
ΔV_{OUT} (Line)/V_{OUT}	Line Regulation Accuracy	V_{OUT} = 1.5V, V_{IN} = 4V to 20V, I_{OUT} = 0A	●		0.04	0.15	%/V
ΔV_{OUT} (Load)/V_{OUT}	Load Regulation Accuracy	V_{OUT} = 1.5V, I_{OUT} = 0A to 3A	●		0.5	1.5	%
$V_{OUT(AC)}$	Output Ripple Voltage	I_{OUT} = 0A, C_{OUT} = 100µF Ceramic, V_{IN} = 12V, V_{OUT} = 1.5V			5		mV
$\Delta V_{OUT(START)}$	Turn-On Overshoot	I_{OUT} = 0A, C_{OUT} = 100µF Ceramic, TRACK/SS = 0.01µF, V_{IN} = 12V, V_{OUT} = 1.5V			30		mV
t_{START}	Turn-On Time	C_{OUT} = 100µF Ceramic, No Load, TRACK/SS = 0.01µF, V_{IN} = 12V, V_{OUT} = 1.5V			2.5		ms
ΔV_{OUTLS}	Peak Deviation for Dynamic Load	Load: 0% to 50% to 0% of Full Load, C_{OUT} = 47µF Ceramic, V_{IN} = 12V, V_{OUT} = 1.5V			80		mV
t_{SETTLE}	Settling Time for Dynamic Load Step	Load: 0% to 50% to 0% of Full Load, C_{OUT} = 47µF Ceramic, V_{IN} = 12V, V_{OUT} = 1.5V			40		µs
I_{OUTPK}	Output Current Limit	V_{IN} = 12V, V_{OUT} = 1.5V		3.5	5		A
V_{FB}	Voltage at FB Pin	I_{OUT} = 0A, V_{OUT} = 1.5V, –40°C to 125°C	●	0.592	0.60	0.606	V
I_{FB}	Current at FB Pin	(Note 4)				±30	nA
R_{FBHI}	Resistor Between V_{OUT} and FB Pins			60.05	60.40	60.75	kΩ
$I_{TRACK/SS}$	Track Pin Soft-Start Pull-Up Current	TRACK/SS = 0V			2	4	µA
$V_{IN(UVLO)}$	V_{IN} Undervoltage Lockout	V_{IN} Falling, SV_{IN} = V_{IN} V_{IN} Hysteresis, SV_{IN} = V_{IN}		2.4	2.6 350	2.8	V mV
$t_{ON(MIN)}$	Minimum On-Time	(Note 4)			40		ns
$t_{OFF(MIN)}$	Minimum Off-Time	(Note 4)			70		ns
V_{PGOOD}	PGOOD Trip Level	V_{FB} With Respect to Set Output V_{FB} Ramping Negative V_{FB} Ramping Positive		 –15 7	 –10 10	 –7 15	 % %

ELECTRICAL CHARACTERISTICS

The ● denotes the specifications which apply over the full internal operating temperature range (Note 2), otherwise specifications are at T_A = 25°C. V_{IN} = SV_{IN} = 12V per the typical application shown on the front page.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
I_{PGOOD}	PGOOD Leakage					2	µA
V_{PGL}	PGOOD Voltage Low	I_{PGOOD} = 1mA			0.02	0.1	V
V_{INTVCC}	Internal V_{CC} Voltage	SV_{IN} = 4V to 20V		3.1	3.3	3.4	V
V_{INTVCC} Load Reg	$INTV_{CC}$ Load Regulation	I_{CC} = 0mA to 20mA			0.5		%
f_{OSC}	Oscillator Frequency	FREQ = OPEN			1		MHz

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: The LTM4623 is tested under pulsed load conditions such that $T_J \approx T_A$. The LTM4623E is guaranteed to meet performance specifications over the 0°C to 125°C internal operating temperature range. Specifications over the –40°C to 125°C internal operating temperature range are assured by design, characterization and correlation with statistical process controls. The LTM4623I is guaranteed to meet specifications over the full –40°C to 125°C internal operating temperature range. Note that the maximum ambient temperature consistent with these specifications is determined by specific operating conditions in conjunction with board layout, the rated package thermal resistance and other environmental factors.

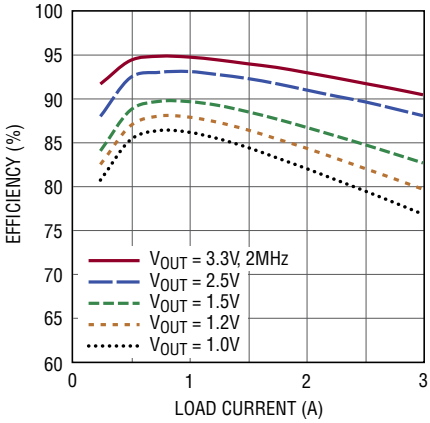
Note 3: See output current derating curves for different V_{IN}, V_{OUT} and T_A.

Note 4: 100% tested at wafer level.

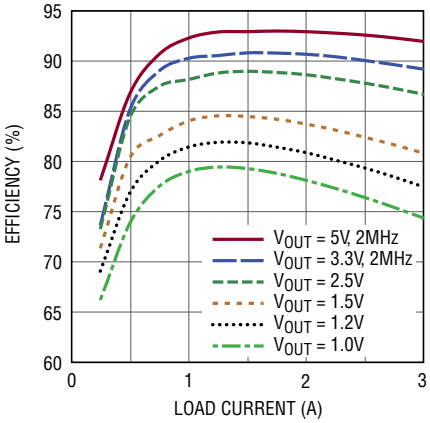
Note 5: This IC includes overtemperature protection that is intended to protect the device during momentary overload conditions. Junction temperature will exceed 125°C when overtemperature protection is active. Continuous operation above the specified maximum operating junction temperature may impair device reliability.

TYPICAL PERFORMANCE CHARACTERISTICS

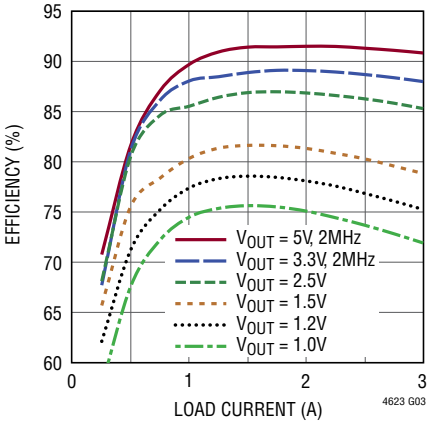
Efficiency vs Load Current with $5V_{IN}$



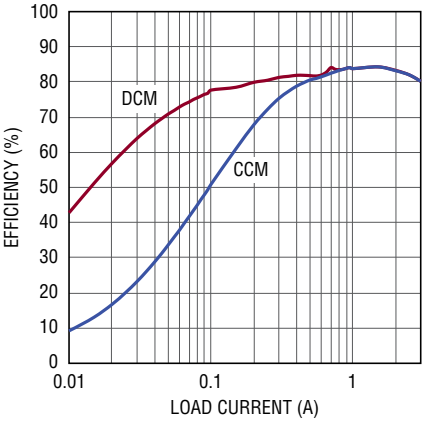
Efficiency vs Load Current with $12V_{IN}$



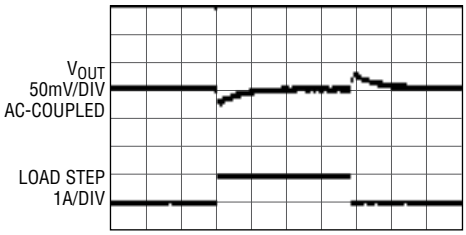
Efficiency vs Load Current with $16V_{IN}$



DCM Mode Efficiency with $12V_{IN}$, $1.5V_{OUT}$

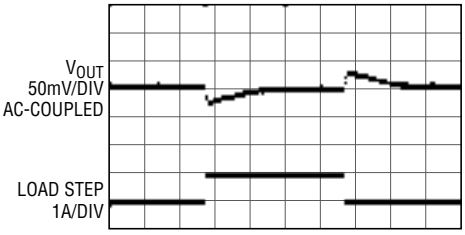


1.0V Output Transient Response



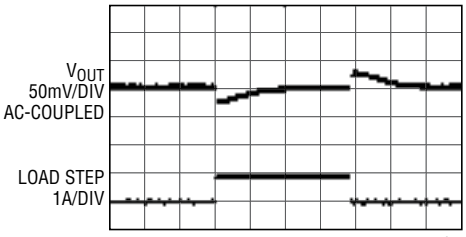
V_{IN} = 12V 20µs/DIV
V_{OUT} = 1.0V
FREQ = 1MHz
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP
LOAD STEP = 2A TO 3A WITH 1A/µS SLEW RATE
FEED FORWARD CAP = 100pF

1.2V Output Transient Response



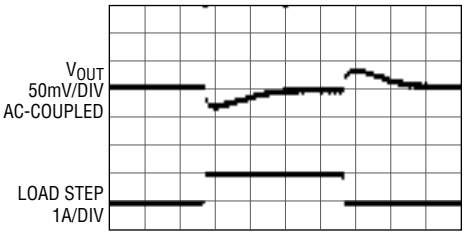
V_{IN} = 12V 20µs/DIV
V_{OUT} = 1.2V
FREQ = 1MHz
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP
LOAD STEP = 2A TO 3A WITH 1A/µS SLEW RATE
FEED FORWARD CAP = 100pF

1.5V Output Transient Response



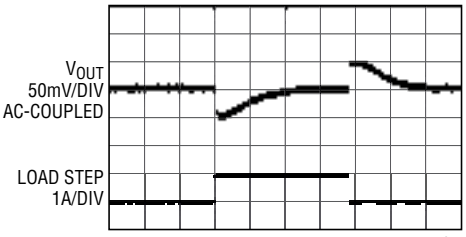
V_{IN} = 12V 20µs/DIV
V_{OUT} = 1.5V
FREQ = 1MHz
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP
LOAD STEP = 2A TO 3A WITH 1A/µS SLEW RATE
FEED FORWARD CAP = 100pF

1.8V Output Transient Response



V_{IN} = 12V 20µs/DIV
V_{OUT} = 1.8V
FREQ = 1MHz
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP
LOAD STEP = 2A TO 3A WITH 1A/µS SLEW RATE
FEED FORWARD CAP = 100pF

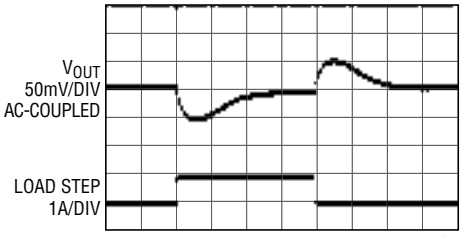
2.5V Output Transient Response



V_{IN} = 12V 20µs/DIV
V_{OUT} = 2.5V
FREQ = 1MHz
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP
LOAD STEP = 2A TO 3A WITH 1A/µS SLEW RATE
FEED FORWARD CAP = 100pF

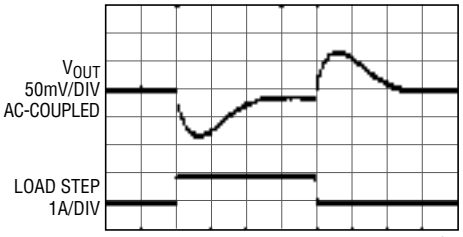
TYPICAL PERFORMANCE CHARACTERISTICS

3.3V Output Transient Response



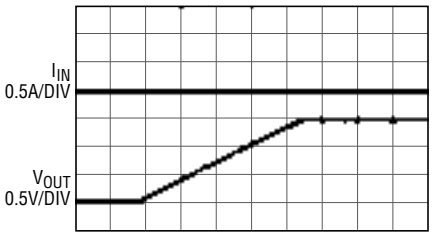
V_{IN} = 12V 20µs/DIV
V_{OUT} = 3.3V
FREQ = 1MHz
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP
LOAD STEP = 2A TO 3A WITH 1A/µS SLEW RATE
FEED FORWARD CAP = 100pF

5V Output Transient Response



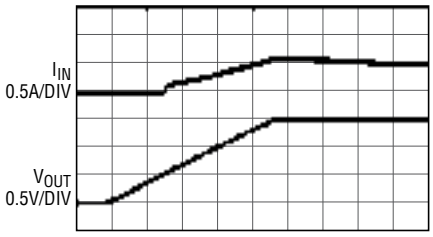
V_{IN} = 12V 20µs/DIV
V_{OUT} = 5V
FREQ = 1MHz
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP
LOAD STEP = 2A TO 3A WITH 1A/µS SLEW RATE
FEED FORWARD CAP = 100pF

Start-Up with No Load Applied



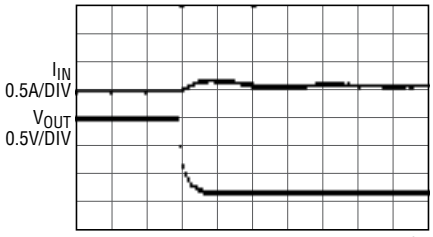
V_{IN} = 12V 5ms/DIV
V_{OUT} = 1.5V
FREQ = 1MHz
INPUT CAPACITOR = 1 × 22µF CERAMIC CAP
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP
SOFT START = 0.1µF

Start-Up with 3A Load Applied



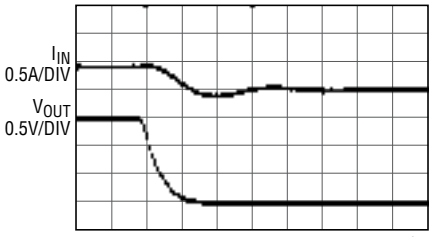
V_{IN} = 12V 5ms/DIV
V_{OUT} = 1.5V
FREQ = 1MHz
INPUT CAPACITOR = 1 × 22µF CERAMIC CAP
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP
SOFT START = 0.1µF

Short Circuit with No Load Applied



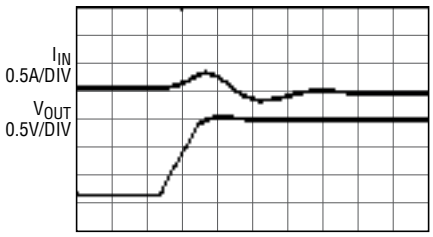
V_{IN} = 12V 5ms/DIV
V_{OUT} = 1.5V
FREQ = 1MHz
INPUT CAPACITOR = 1 × 22µF CERAMIC CAP
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP

Short Circuit with 3A Load Applied



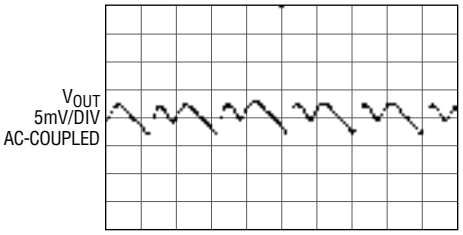
V_{IN} = 12V 20µs/DIV
V_{OUT} = 1.5V
FREQ = 1MHz
INPUT CAPACITOR = 1 × 22µF CERAMIC CAP
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP

Short Circuit with 3A Load Applied



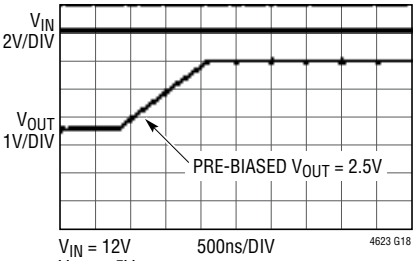
V_{IN} = 12V 20µs/DIV
V_{OUT} = 1.5V
FREQ = 1MHz
INPUT CAPACITOR = 1 × 22µF CERAMIC CAP
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP

Output Ripple



V_{IN} = 12V 500ns/DIV
V_{OUT} = 5V
FREQ = 1MHz
INPUT CAPACITOR = 1 × 22µF CERAMIC CAP
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP

Start into Pre-Biased Output



V_{IN} = 12V 500ns/DIV
V_{OUT} = 5V
FREQ = 1MHz
PRE-BIASED V_{OUT} = 2.5V
INPUT CAPACITOR = 1 × 22µF CERAMIC CAP
OUTPUT CAPACITOR = 1 × 47µF CERAMIC CAP

PIN FUNCTIONS

PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY.

COMP (A1): Current Control Threshold and Error Amplifier Compensation Point. The current comparator's trip threshold is linearly proportional to this voltage, whose normal range is from 0.3V to 1.8V. Tie the COMP pins together for parallel operation. The device is internally compensated. This is an output pin. Do not force a voltage on this pin.

TRACK/SS (A2): Output Tracking and Soft-Start Input. Allows the user to control the rise time of the output voltage. Putting a voltage below 0.6V on this pin bypasses the internal reference input to the error amplifier, and servos the FB pin to match the TRACK/SS voltage. Above 0.6V, the tracking function stops and the internal reference resumes control of the error amplifier. There's an internal 2µA pull-up current from $INTV_{CC}$ on this pin, so putting a capacitor here provides a soft-start function.

RUN (A3): Run Control Input of the Switching Mode Regulator. Enables chip operation by tying RUN above 1.2V. Pulling it below 1.1V shuts down the part. Do not leave floating.

FREQ (A4): Frequency is set internally to 1MHz. An external resistor can be placed from this pin to SGND to increase frequency, or from this pin to $INTV_{CC}$ to reduce frequency. See the Applications Information section for frequency adjustment.

FB (B1): The Negative Input of the Error Amplifier. Internally, this pin is connected to V_{OUT} with a 60.4k precision resistor. Different output voltages can be programmed with an additional resistor between the FB and SGND pins. Tying the FB pins together allows for parallel operation. See the Applications Information section for details.

PHMODE (B2): Control Input to Phase Selector of the Switching Mode Regulator Channel. This pin determines the phase relationship between internal oscillator and CLKOUT signal. Tie it to $INTV_{CC}$ for 2-phase operation, tie it to SGND for 3-phase operation, and tie it to $INTV_{CC}/2$ for 4-phase operation.

GND (B3, C3, D3-D4, E3): Power Ground Pins for Both Input and Output Returns.

SGND (B4): Signal Ground Connection. Tie to GND with minimum distance. Connect FREQ resistor, COMP component, MODE, TRACK/SS component, FB resistor to this pin as needed.

V_{OUT} (C1, D1-D2, E1-E2): Power Output Pins. Apply output load between these pins and GND pins. Recommend placing output decoupling capacitance directly between these pins and GND pins.

PGOOD (C2): Output Power Good with Open-Drain Logic. PGOOD is pulled to ground when the voltage on the FB pin is not within ±10% of the internal 0.6V reference.

MODE (C4): Operation Mode Select. Tie this pin to $INTV_{CC}$ to force continuous synchronous operation at all output loads. Tying it to SGND enables discontinuous mode operation at light loads. Do not leave floating.

SV_{IN} (C5): Signal V_{IN}. Input voltage to the on-chip 3.3V regulator. Tie this pin to the V_{IN} pin in most applications. Otherwise connect SV_{IN} to an external voltage supply of at least 4V which must also be greater than V_{OUT}.

V_{IN} (D5, E5): Power Input Pins. Apply input voltage between these pins and GND pins. Recommend placing input decoupling capacitance directly between V_{IN} pins and GND pins.

$INTV_{CC}$ (E4): Internal 3.3V Regulator Output. The internal power drivers and control circuits are powered from this voltage. This pin is internally decoupled to GND with a 1µF low ESR ceramic capacitor.

CLKIN (A5): External Synchronization Input to Phase Detector of the Switching Mode Regulator. This pin is internally terminated to SGND with 20k. The phase-locked loop will force the top power NMOS's turn-on signal to be synchronized with the rising edge of the CLKIN signal.

CLKOUT (B5): Output Clock Signal for PolyPhase Operation of the Switching Mode Regulator. The phase of CLKOUT with respect to CLKIN is determined by the state of the PHMODE pin. CLKOUT's peak-to-peak amplitude is $INTV_{CC}$ to GND. This is an output pin. Do not force a voltage on this pin.

BLOCK DIAGRAM

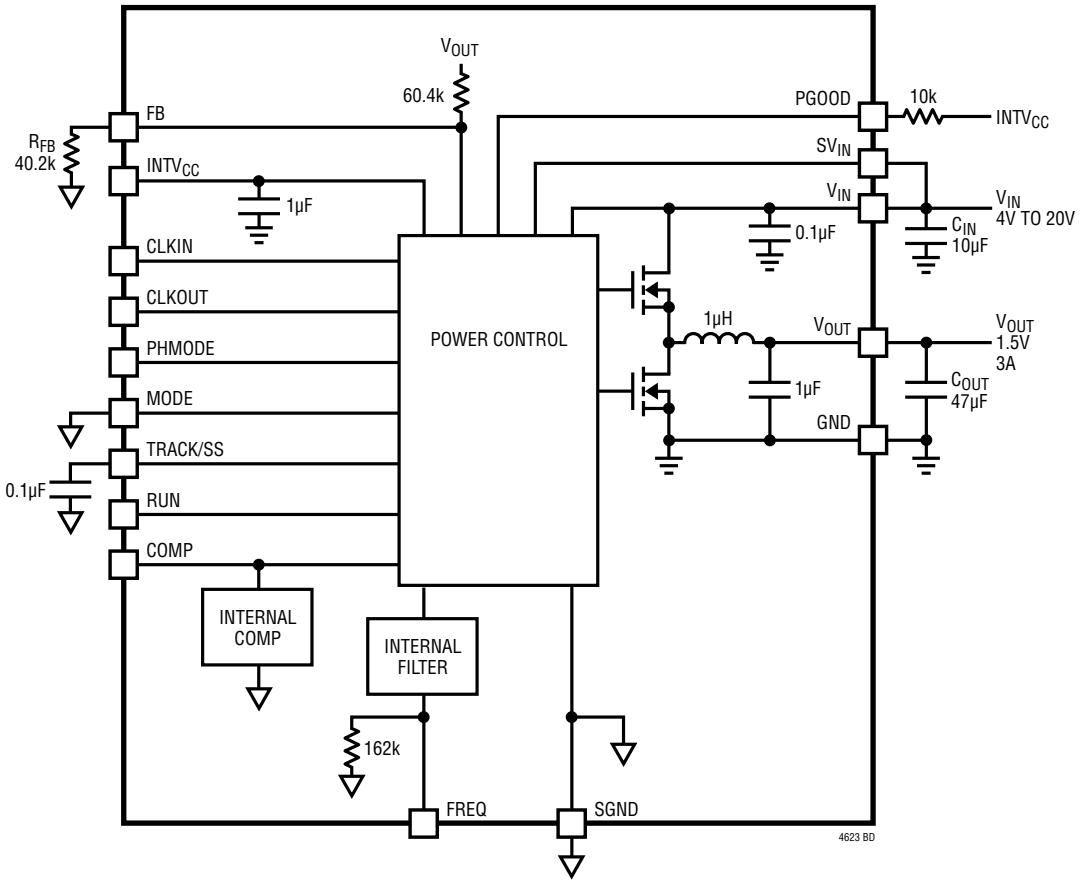


Figure 1. Simplified LTM4623 Block Diagram

DECOUPLING REQUIREMENTS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
C_{IN}	External Input Capacitor Requirement (V_{IN} = 4V to 20V, V_{OUT} = 1.5V)	I_{OUT} = 3A	4.7	10		µF
C_{OUT}	External Output Capacitor Requirement (V_{IN} = 4V to 20V, V_{OUT} = 1.5V)	I_{OUT} = 3A	22	47		µF

OPERATION

The LTM4623 is a standalone nonisolated switch mode DC/DC power supply. It can deliver up to 3A DC output current with few external input and output capacitors. This module provides precisely regulated output voltage adjustable between 0.6V to 5.5V via one external resistor over a 4V to 20V input voltage range. With an external bias supply above 4V connected to SV_{IN}, this module operates with an input voltage down to 2.375V. The typical application schematic is shown in Figure 24.

The LTM4623 contains an integrated constant on-time valley current mode regulator, power MOSFETs, inductor, and other supporting discrete components. The default switching frequency is 1MHz. For output voltages between 3.3V and 5.5V, an external 162k resistor is required between FREQ and SGND pins to set the operating frequency to 2MHz to optimize inductor current ripple. For switching noise-sensitive applications, the switching frequency can be adjusted by external resistors and the µModule regulator can be externally synchronized to a clock within ±30% of the set frequency. See the Applications Information section.

With current mode control and internal feedback loop compensation, the LTM4623 module has sufficient stability margins and good transient performance with a wide range of output capacitors, even with all ceramic output capacitors.

Current mode control provides cycle-by-cycle fast current limiting. Foldback current limiting is provided in an overcurrent condition indicated by a drop in V_{FB} reducing inductor valley current to approximately 40% of the original value. Internal output overvoltage and undervoltage comparators pull the open-drain PGOOD output low if the output feedback voltage exits a ±10% window around the regulation point. Continuous operation is forced during OV and UV condition except during start-up when the TRACK pin is ramping up to 0.6V.

Furthermore, in order to protect the internal power MOSFET devices against transient voltage spikes, the LTM4623 constantly monitors the V_{IN} pin for an overvoltage condition. When V_{IN} rises above 23.5V, the regulator suspends operation by shutting off both power MOSFETs. Once V_{IN} drops below 21.5V, the regulator immediately resumes normal operation. The regulator does not execute its soft-start function when exiting an overvoltage condition.

Multiphase operation can be easily employed with the synchronization and phase mode controls. Up to 12 phases can be cascaded to run simultaneously with respect to each other by programming the PHMODE pin to different levels. The LTM4623 has CLKIN and CLKOUT pins for PolyPhase operation of multiple devices or frequency synchronization.

Pulling the RUN pin below 1.1V forces the controller into its shutdown state, turning off both power MOSFETs and most of the internal control circuitry. At light load currents, discontinuous mode (DCM) operation can be enabled to achieve higher efficiency compared to continuous mode (CCM) by pulling the MODE pin to SGND. The TRACK/SS pin is used for power supply tracking and soft-start programming. See the Applications Information section.

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The typical LTM4623 application circuit is shown in Figure 24. External component selection is primarily determined by the input voltage, the output voltage and the maximum load current. Refer to Table 7 for specific external capacitor requirements for a particular application.

V_{IN} to V_{OUT} Step-Down Ratios

There are restrictions in the maximum V_{IN} and V_{OUT} step-down ratios that can be achieved for a given input voltage due to the minimum off-time and minimum on-time limits of the regulator. The minimum off-time limit imposes a maximum duty cycle which can be calculated as:

$$D_{MAX} = 1 - (t_{OFF(MIN)} \bullet f_{SW})$$

where $t_{OFF(MIN)}$ is the minimum off-time, typically 70ns for LTM4623, and f_{SW} (Hz) is the switching frequency. Conversely the minimum on-time limit imposes a minimum duty cycle of the converter which can be calculated as:

$$D_{MIN} = t_{ON(MIN)} \bullet f_{SW}$$

where $t_{ON(MIN)}$ is the minimum on-time, typically 40ns for LTM4623. In the rare cases where the minimum duty cycle is surpassed, the output voltage will still remain in regulation, but the switching frequency will decrease from its programmed value. Note that additional thermal derating may be applied. See the Thermal Considerations and Output Current Derating section in this data sheet.

Output Voltage Programming

The PWM controller has an internal 0.6V reference voltage. As shown in the Block Diagram, a 60.4k internal feedback resistor connects the V_{OUT} and FB pins together. Adding a resistor, R_{FB}, from FB pin to SGND programs the output voltage:

$$R_{FB} = \frac{0.6V}{V_{OUT} - 0.6V} \bullet 60.4k$$

Table 1. R_{FB} Resistor Table vs Various Output Voltages

V_{OUT} (V)	0.6	1.0	1.2	1.5	1.8	2.5	3.3	5.0
R_{FB} (kΩ)	OPEN	90.9	60.4	40.2	30.1	19.1	13.3	8.25

Pease note that for 3.3V and 5V output, a higher operating frequency (2MHz) is required to optimize inductor current ripple. See Operating Frequency section.

For parallel operation of N-channels LTM4623, tie all the FB pins together and use the following equation to solve for R_{FB}:

$$R_{FB} = \frac{0.6V}{V_{OUT} - 0.6V} \bullet \frac{60.4k}{N}$$

Input Decoupling Capacitors

The LTM4623 module should be connected to a low AC impedance DC source. For the regulator, a 10µF input ceramic capacitor is required for RMS ripple current decoupling. Bulk input capacitance is only needed when the input source impedance is compromised by long inductive leads, traces or not enough source capacitance. The bulk capacitor can be an aluminum electrolytic capacitor or polymer capacitor.

Without considering the inductor ripple current, the RMS current of the input capacitor can be estimated as:

$$I_{CIN(RMS)} = \frac{I_{OUT(MAX)}}{\eta\%} \bullet \sqrt{D \bullet (1-D)}$$

where $\eta\%$ is the estimated efficiency of the power module.

Output Decoupling Capacitors

With an optimized high frequency, high bandwidth design, only a single low ESR output ceramic capacitor is required for the LTM4623 to achieve low output ripple voltage and very good transient response. Additional output filtering may be required by the system designer if further reduction of output ripple or dynamic transient spikes is required. Table 7 shows a matrix of different output voltages and output capacitors to minimize the voltage droop and overshoot during a 1A load-step transient. The Linear Technology LTpowerCAD™ design tool is available to download online for output ripple, stability and transient response analysis for further optimization.

Discontinuous Current Mode (DCM)

In applications where low output ripple and high efficiency at intermediate current are desired, discontinuous current mode (DCM) should be used by connecting the MODE pin

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to SGND. At light loads the internal current comparator may remain tripped for several cycles and force the top MOSFET to stay off for several cycles, thus skipping cycles. The inductor current does not reverse in this mode.

Forced Continuous Current Mode (CCM)

In applications where fixed frequency operation is more critical than low current efficiency, and where the lowest output ripple is desired, forced continuous operation should be used. Forced continuous operation can be enabled by tying the MODE pin to $INTV_{CC}$. In this mode, inductor current is allowed to reverse during low output loads, the COMP voltage is in control of the current comparator threshold throughout, and the top MOSFET always turns on with each oscillator pulse. During start-up, forced continuous mode is disabled and inductor current is prevented from reversing until the LTM4623's output voltage is in regulation.

Operating Frequency

The operating frequency of the LTM4623 is optimized to achieve the compact package size and the minimum output ripple voltage while still keeping high efficiency. The default operating frequency is internally set to 1MHz. In most applications, no additional frequency adjusting is required.

If any operating frequency other than 1MHz is required by application, the operating frequency can be increased by adding a resistor, RFSET, between the FREQ pin and SGND, as shown in Figure 28. The operating frequency can be calculated as:

$$f(Hz) = \frac{1.6e11}{162k \,||\, R_{FSET}(\Omega)}$$

To reduce switching current ripple, 2MHz operating frequency is required for 3.3V to 5.5V output with R_{FSET} = 162k to SGND.

The operating frequency can also be decreased by adding a resistor between the FREQ pin and $INTV_{CC}$, calculated as:

$$f(Hz) = 1MHz - \frac{2.8e11}{R_{FSET}(\Omega)}$$

The programmable operating frequency range is from 800kHz to 4MHz.

Please note a minimum switching frequency is required for given V_{IN}, V_{OUT} operating conditions to keep a maximum peak-to-peak inductor ripple current below 2A for the LTM4623.

The peak-to-peak inductor ripple current can be calculated as:

$$\Delta I_{P-P} = V_{OUT}\left(1-\frac{V_{OUT}}{V_{IN}}\right)\bullet\frac{1}{f_{SW}(MHz)}$$

The maximum 2A peak-to-peak inductor ripple current is enforced due to the nature of the valley current mode control to maintain output voltage regulation at no load.

Frequency Synchronization and Clock In

The power module has a phase-locked loop comprised of an internal voltage controlled oscillator and a phase detector. This allows the internal top MOSFET turn-on to be locked to the rising edge of the external clock. The external clock frequency range must be within ±30% around the set operating frequency. A pulse detection circuit is used to detect a clock on the CLKIN pin to turn on the phase-locked loop. The pulse width of the clock has to be at least 100ns. The clock high level must be above 2V and clock low level below 0.3V. During the start-up of the regulator, the phase-locked loop function is disabled.

Multiphase Operation

For output loads that demand more than 3A of current, multiple LTM4623s can be paralleled to run out of phase to provide more output current without increasing input and output voltage ripples.

The CLKOUT signal can be connected to the CLKIN pin of the following LTM4623 stage to line up both the frequency and the phase of the entire system. Tying the PHMODE pin to INTVCC, SGND or $INTV_{CC}$/2 generates a phase difference (between CLKIN and CLKOUT) of 180°, 120°, or 90° respectively, which corresponds to 2-phase, 3-phase or 4-phase operation. A total of 12 phases can be cascaded

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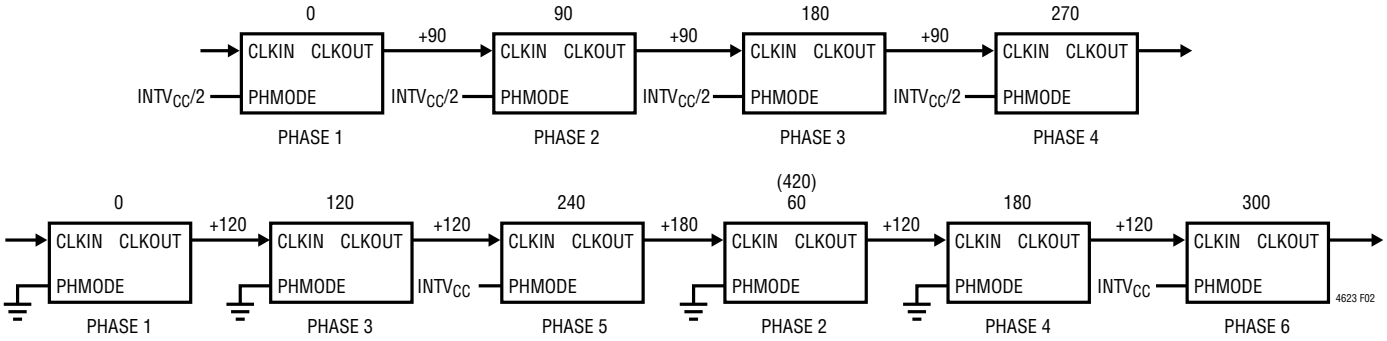

Figure 2. 4-Phase, 6-Phase Operation

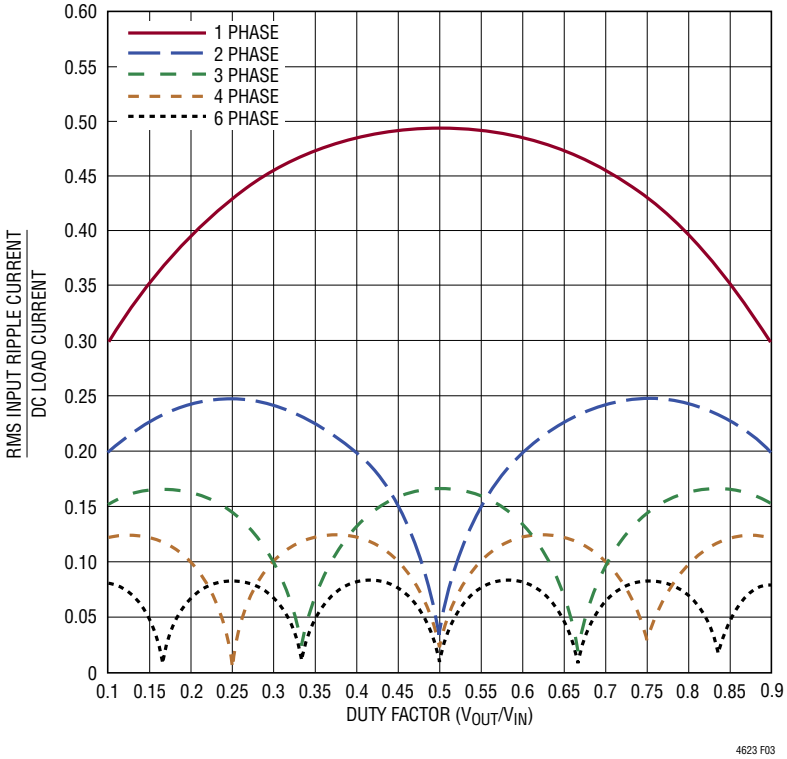

Figure 3. RMS Input Ripple Current to DC Load Current Ratio as a Function of Duty Cycle

to run simultaneously out-of-phase with respect to each other by programming the PHMODE pin of each LTM4623 to different levels. Figure 2 shows a 4-phase design and a 6-phase design example for clock phasing.

Table 2. PHMODE Pin Status and Corresponding Phase Relationship (Relate to CLKIN)

PHASMD	$INTV_{CC}$	SGND	$INTV_{CC}/2$
CLKOUT	180°	120°	90°

A multiphase power supply significantly reduces the amount of ripple current in both the input and output capacitors. The RMS input ripple current is reduced by, and the effective ripple frequency is multiplied by, the number of phases used (assuming that the input voltage is greater than the number of phases used times the output voltage). The output ripple amplitude is also reduced by the number of phases used when all of the outputs are tied together to achieve a single high output current design.

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The LTM4623 device is an inherently current mode controlled device, so parallel modules will have very good current sharing. This will balance the thermals on the design. Please tie the RUN, TRACK/SS, FB and COMP pins of each paralleling module together. Figure 26 shows an example of parallel operation and pin connection.

Input RMS Ripple Current Cancellation

Application Note 77 provides a detailed explanation of multiphase operation. The input RMS ripple current cancellation mathematical derivations are presented, and a graph is displayed representing the RMS ripple current reduction as a function of the number of interleaved phases. Figure 3 shows this graph.

Soft-Start And Output Voltage Tracking

The TRACK/SS pin provides a means to either soft start the regulator or track it to a different power supply. A capacitor on the TRACK/SS pin will program the ramp rate of the output voltage. An internal 2µA current source will charge up the external soft-start capacitor towards $INTV_{CC}$ voltage. When the TRACK/SS voltage is below 0.6V, it will take over the internal 0.6V reference voltage to control the output voltage. The total soft-start time can be calculated as:

$$t_{SS} = 0.6 \bullet \frac{C_{SS}}{2\mu A}$$

where C_{SS} is the capacitance on the TRACK/SS pin. Current foldback and forced continuous mode are disabled during the soft-start process.

Output voltage tracking can also be programmed externally using the TRACK/SS pin. The output can be tracked up and down with another regulator. Figure 4 and Figure 5 show an example waveform and schematic of ratiometric tracking where the slave regulator's output slew rate is proportional to the master's.

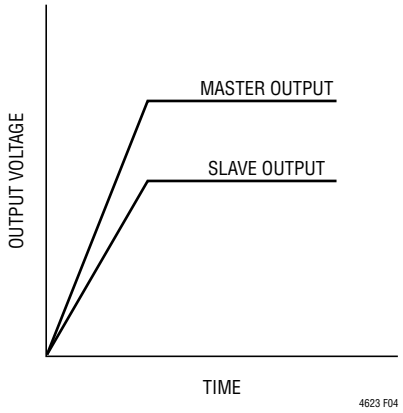

Figure 4. Output Ratiometric Tracking Waveform

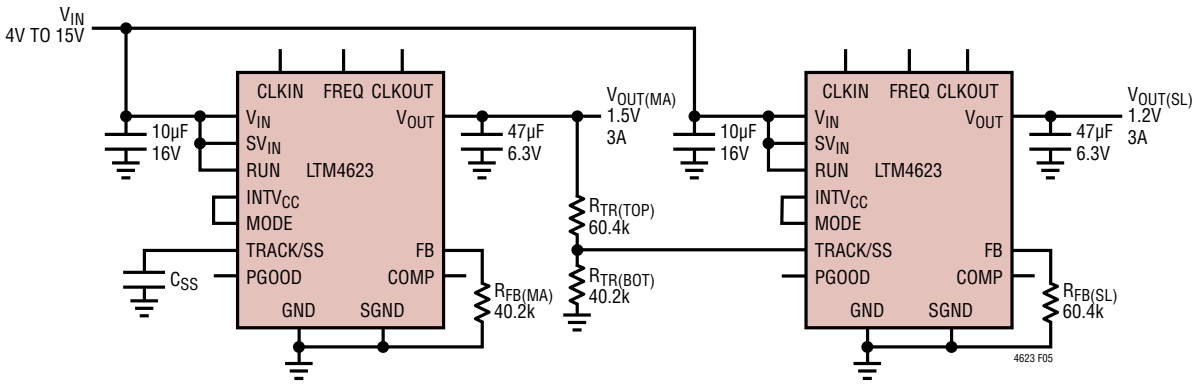

Figure 5. Example Schematic of Ratiometric Output Voltage Tracking

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Since the slave regulator's TRACK/SS is connected to the master's output through a $R_{TR(TOP)}/R_{TR(BOT)}$ resistor divider and its voltage used to regulate the slave output voltage when TRACK/SS voltage is below 0.6V, the slave output voltage and the master output voltage should satisfy the following equation during start-up:

$$V_{OUT(SL)} \bullet \frac{R_{FB(SL)}}{R_{FB(SL)} + 60.4k} = V_{OUT(MA)} \bullet \frac{R_{TR(BOT)}}{R_{TR(TOP)} + R_{TR(BOT)}}$$

The $R_{FB(SL)}$ is the feedback resistor and the $R_{TR(TOP)}/R_{TR(BOT)}$ is the resistor divider on the TRACK/SS pin of the slave regulator, as shown in Figure 5.

Following the previous equation, the ratio of the master's output slew rate (MR) to the slave's output slew rate (SR) is determined by:

$$\frac{MR}{SR} = \frac{\frac{R_{FB(SL)}}{R_{FB(SL)} + 60.4k}}{\frac{R_{TR(BOT)}}{R_{TR(TOP)} + R_{TR(BOT)}}}$$

For example, $V_{OUT(MA)}$=1.5V, MR = 1.5V/1ms and $V_{OUT(SL)}$ = 1.2V, SR = 1.2V/1ms. From the equation, we could solve that $R_{TR(TOP)}$ = 60.4k and $R_{TR(BOT)}$ = 40.2k are a good combination for the ratiometric tracking.

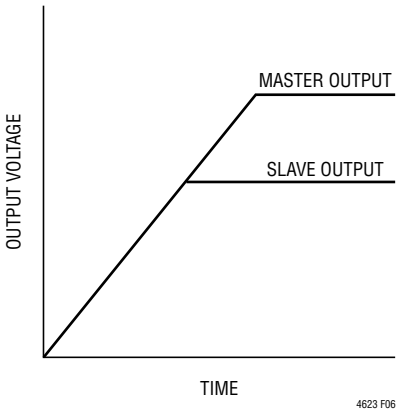

Figure 6. Output Coincident Tracking Waveform

The TRACK/SS pin will have the 2µA current source on when a resistive divider is used to implement tracking on the slave regulator. This will impose an offset on the TRACK/SS pin input. Smaller value resistors with the same ratios as the resistor values calculated from the above equation can be used. For example, where the 60.4k is used then a 6.04k can be used to reduce the TRACK/SS pin offset to a negligible value.

The coincident output tracking can be recognized as a special ratiometric output tracking in which the master's output slew rate (MR) is the same as the slave's output slew rate (SR), waveform as shown in Figure 6.

From the equation, we could easily find that, in coincident tracking, the slave regulator's TRACK/SS pin resistor divider is always the same as its feedback divider:

$$\frac{R_{FB(SL)}}{R_{FB(SL)} + 60.4k} = \frac{R_{TR(BOT)}}{R_{TR(TOP)} + R_{TR(BOT)}}$$

For example, $R_{TR(TOP)}$ = 60.4k and $R_{TR(BOT)}$ = 60.4k is a good combination for coincident tracking for a $V_{OUT(MA)}$ = 1.5V and $V_{OUT(SL)}$ = 1.2V application.

Power Good

The PGOOD pin is an open-drain pin that can be used to monitor valid output voltage regulation. This pin is pulled low when the output voltage exceeds a ±10% window around the regulation point. To prevent unwanted PGOOD glitches during transients or dynamic V_{OUT} changes, the LTM4623's PGOOD falling edge includes a blanking delay of approximately 52 switching cycles.

Stability Compensation

The LTM4623's internal compensation loop is designed and optimized for use with low ESR ceramic output capacitors. Table 7 is provided for most application requirements. In case more phase margin is required for the application, an additional 100pF feedforward capacitor (C_{FF}) can be placed between the V_{OUT} and FB pins. The LTpowerCAD design tool is available for control loop optimization.

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RUN Enable

Pulling the RUN pin to ground forces the LTM4623 into its shutdown state, turning off both power MOSFETs and most of its internal control circuitry. Bringing the RUN pin above 0.7V turns on the internal reference only, while still keeping the power MOSFETs off. Increasing the RUN pin voltage above 1.2V will turn on the entire chip.

Low Input Application

The LTM4623 module has a separate SV_{IN} pin which makes it suitable for low input voltage applications down to 2.375V. The SV_{IN} pin is the single input of the whole control circuitry while the V_{IN} pin is the power input which directly connects to the drain of the top MOSFET. In most applications where V_{IN} is greater than 4V, connect SV_{IN} directly to V_{IN} with a short trace. An optional filter, consisting of a resistor (1Ω to 10Ω) between SV_{IN} and V_{IN} along with a 0.1µF bypass capacitor between SV_{IN} and ground, can be placed for additional noise immunity. This filter is not necessary in most cases if good PCB layout practices are followed (see Figure 23). In a low input voltage application (2.375V to 4V), connect SV_{IN} to an external voltage higher than 4V with 1µF local bypass capacitor. See Operating Frequency section. Figure 25 shows an example of a low input voltage application. Please note the SV_{IN} voltage cannot go below the V_{OUT} voltage.

Pre-Biased Output Start-Up

There may be situations that require the power supply to start up with a pre-bias on the output capacitors. In this case, it is desirable to start up without discharging that output pre-bias. The LTM4623 can safely power up into a pre-biased output without discharging it.

The LTM4623 accomplishes this by forcing discontinuous mode (DCM) operation until the TRACK/SS pin voltage reaches 0.6V reference voltage. This will prevent the BG from turning on during the pre-biased output start-up which would discharge the output.

Please do not pre-bias LTM4623 with a voltage higher than $INTV_{CC}$ (3.3V) voltage or a voltage higher than the output voltage set by the feedback resistor (R_{FB}).

Overtemperature Protection

The internal overtemperature protection monitors the junction temperature of the module. If the junction temperature reaches approximately 160°C, both power switches will be turned off until the temperature drops about 15°C cooler.

Radiated EMI Noise

High radiated EMI noise is a disadvantage for switching regulators by nature. Fast switching turn-on and turn-off make the large di/dt change in the converters, which act as the radiation sources in most systems. LTM4623 integrates the feature to minimize the radiated EMI noise to meet the most applications with low noise requirements. It is fully compliant with the EN55022 Class B Standard.

Thermal Considerations and Output Current Derating

The thermal resistances reported in the Pin Configuration section of the data sheet are consistent with those parameters defined by JESD 51-12 and are intended for use with finite element analysis (FEA) software modeling tools that leverage the outcome of thermal modeling, simulation, and correlation to hardware evaluation performed on a µModule package mounted to a hardware test board. The motivation for providing these thermal coefficients is found in JESD 51-12 (Guidelines for Reporting and Using Electronic Package Thermal Information).

Many designers may opt to use laboratory equipment and a test vehicle such as the demo board to anticipate the µModule regulator's thermal performance in their application at various electrical and environmental operating conditions to compliment any FEA activities. Without FEA software, the thermal resistances reported in the Pin Configuration section are, in and of themselves, not relevant to providing guidance of thermal performance; instead, the derating curves provided in this data sheet can be used in a manner that yields insight and guidance pertaining to one's application usage, and can be adapted to correlate thermal performance to one's own application.

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The Pin Configuration section gives four thermal coefficients explicitly defined in JESD 51-12; these coefficients are quoted or paraphrased next:

1. θ_{JA}, the thermal resistance from junction to ambient, is the natural convection junction-to-ambient air thermal resistance measured in a one cubic foot sealed enclosure. This environment is sometimes referred to as "still air" although natural convection causes the air to move. This value is determined with the part mounted to a 95mm × 76mm PCB with four layers.

2. $\theta_{JCbottom}$, the thermal resistance from junction to the bottom of the product case, is determined with all of the component power dissipation flowing through the bottom of the package. In the typical µModule regulator, the bulk of the heat flows out the bottom of the package, but there is always heat flow out into the ambient environment. As a result, this thermal resistance value may be useful for comparing packages, but the test conditions don't generally match the user's application.

3. θ_{JCtop}, the thermal resistance from junction to top of the product case, is determined with nearly all of the component power dissipation flowing through the top of the package. As the electrical connections of the typical µModule regulator are on the bottom of the package, it is rare for an application to operate such that most of the heat flows from the junction to the top of the part. As in the case of $\theta_{JCbottom}$, this value may be useful for comparing packages but the test conditions don't generally match the user's application.

4. θ_{JB}, the thermal resistance from junction to the printed circuit board, is the junction-to-board thermal resistance where almost all of the heat flows through the bottom of the µModule package and into the board, and is really the sum of the $\theta_{JCbottom}$ and the thermal resistance of the bottom of the part through the solder joints and through a portion of the board. The board temperature is measured a specified distance from the package.

A graphical representation of the aforementioned thermal resistances is given in Figure 7; blue resistances are contained within the µModule regulator, whereas green resistances are external to the µModule package.

As a practical matter, it should be clear to the reader that no individual or sub-group of the four thermal resistance parameters defined by JESD 51-12 or provided in the Pin Configuration section replicates or conveys normal operating conditions of a µModule regulator. For example, in normal board-mounted applications, never does 100% of the device's total power loss (heat) thermally conduct exclusively through the top or exclusively through bottom of the µModule package—as the standard defines for θ_{JCtop} and $\theta_{JCbottom}$, respectively. In practice, power loss is thermally dissipated in both directions away from the package—granted, in the absence of a heat sink and airflow, a majority of the heat flow is into the board.

Within the LTM4623 be aware there are multiple power devices and components dissipating power, with a consequence that the thermal resistances relative to different junctions of components or die are not exactly linear with

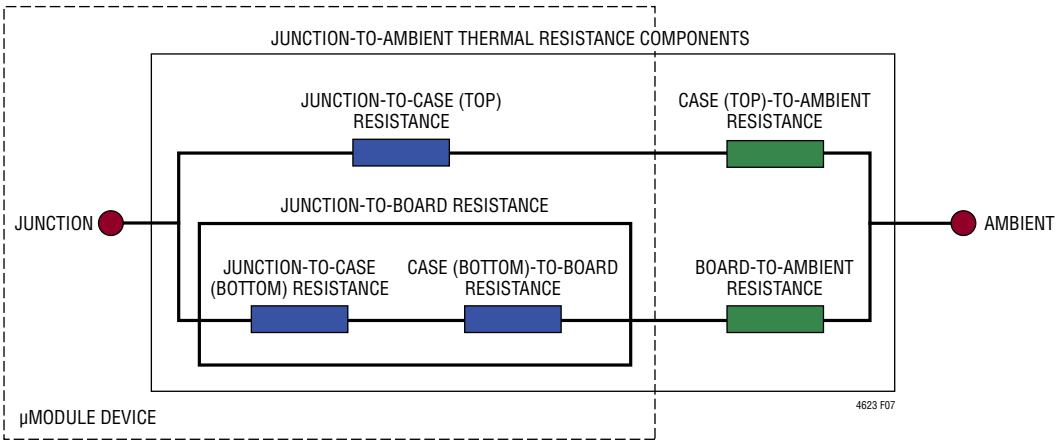

Figure 7. Graphical Representation of JESD 51-12 Thermal Coefficients

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respect to total package power loss. To reconcile this complication without sacrificing modeling simplicity—but also, not ignoring practical realities—an approach has been taken using FEA software modeling along with laboratory testing in a controlled environment chamber to reasonably define and correlate the thermal resistance values supplied in this data sheet: (1) Initially, FEA software is used to accurately build the mechanical geometry of the LTM4623 and the specified PCB with all of the correct material coefficients along with accurate power loss source definitions; (2) this model simulates a software-defined JEDEC environment consistent with JESD 51-12 to predict power loss heat flow and temperature readings at different interfaces that enable the calculation of the JEDEC-defined thermal resistance values; (3) the model and FEA software is used to evaluate the LTM4623 with heat sink and airflow; (4) having solved for and analyzed these thermal resistance values and simulated various operating conditions in the software model, a thorough laboratory evaluation replicates the simulated conditions with thermocouples within a controlled environment chamber while operating the device at the same power loss as that which was simulated. An outcome of this process and due diligence yields the set of derating curves shown in this data sheet. After these laboratory tests have been performed and correlated to the LTM4623 model, then the θ_{JB} and θ_{BA} are summed together to provide a value that should closely equal the θ_{JA} value because approximately 100% of power loss flows from the junction through the board into ambient with no airflow or top mounted heat sink.

The 1.0V, 1.5V, 3.3V and 5V loss curves in Figures 8 to 11 can be used in coordination with the load current derating curves in Figures 12 to 22 for calculating an approximate θ_{JA} thermal resistance for the LTM4623 with various airflow conditions. The power loss curves are taken at room temperature, and are increased with a multiplicative factor according to the ambient temperature. This approximate factor is: 1.3 for 120°C at junction temperature. Maximum load current is achievable while increasing ambient temperature as long as the junction temperature is less than 120°C, which is a 5°C guard band from maximum junction temperature of 125°C. When the ambient temperature reaches a point where the junction temperature is 120°C, then the load current is lowered to maintain the junction at 120°C while increasing ambient temperature up to 120°C. The derating curves are plotted with the output current starting at 3A and the ambient temperature at 30°C. The output voltages are 1.0V, 1.5V, 3.3V and 5V. These are chosen to include the lower and higher output voltage ranges for correlating the thermal resistance. Thermal models are derived from several temperature measurements in a controlled temperature chamber along with thermal modeling analysis. The junction temperatures are monitored while ambient temperature is increased with and without airflow. The power loss increase with ambient temperature change is factored into the derating curves. The junctions are maintained at 120°C maximum while lowering output current or power with increasing ambient temperature. The decreased output current will decrease the internal module loss as ambient temperature is increased. The monitored junction temperature of 120°C minus the ambient operating temperature specifies how much module temperature rise can be allowed. As an example, in Figure 16 the load current is derated to 2.5A at ~95°C with no air flow or heat sink and the power loss for the 12V to 1.5V at 2.5A output is about 1.0W. The 1.0W loss is calculated with the ~0.8W room temperature loss from the 12V to 1.5V power loss curve at 2.5A in Figure 9, and the 1.3 multiplying factor at 120°C junction temperature. If the 95°C ambient temperature is subtracted from the 120°C junction temperature, then the difference of 25°C divided by 1.0W equals a 25°C/W θ_{JA} thermal resistance. Table 4 specifies a 25°C/W value which is very close. Table 3 to Table 6 provide equivalent thermal resistances for 1.0V to 5V outputs with and without airflow. The derived thermal resistances in Table 3 to Table 6 for the various conditions can be multiplied by the calculated power loss as a function of ambient temperature to derive temperature rise above ambient, thus maximum junction temperature. Room temperature power loss can be derived from the efficiency curves in the Typical Performance Characteristics section and adjusted with the above ambient temperature multiplicative factors. The printed circuit board is a 1.6mm thick 4-layer board with two ounce copper for the two outer layers and one ounce copper for the two inner layers. The PCB dimensions are 95mm × 76mm.

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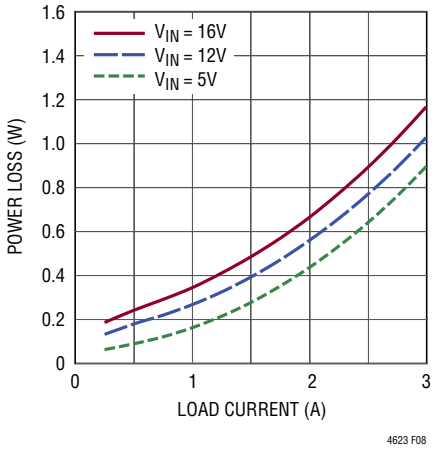


Figure 8. 1.0V Output Power Loss

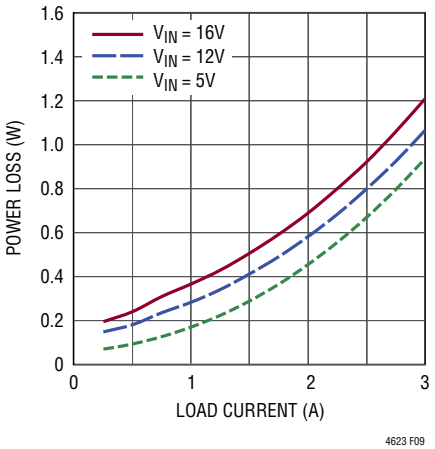


Figure 9. 1.5V Output Power Loss

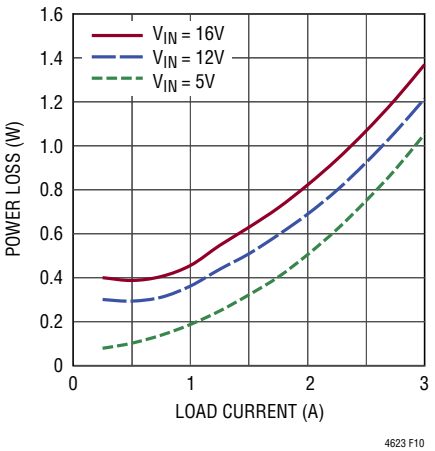


Figure 10. 3.3V Output Power Loss

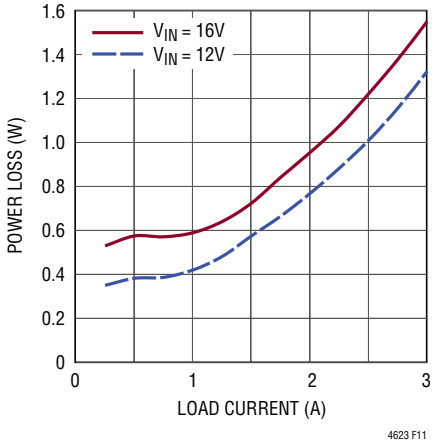


Figure 11. 5V Output Power Loss

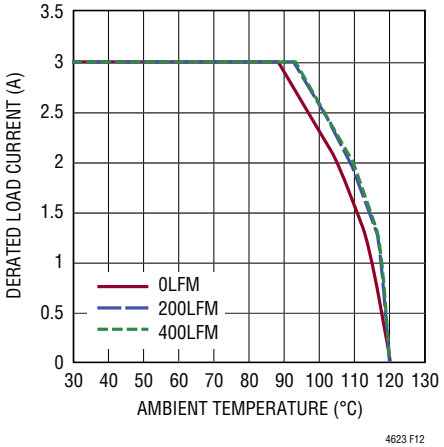


Figure 12. 5V to 1V Derating Curve, No Heat Sink

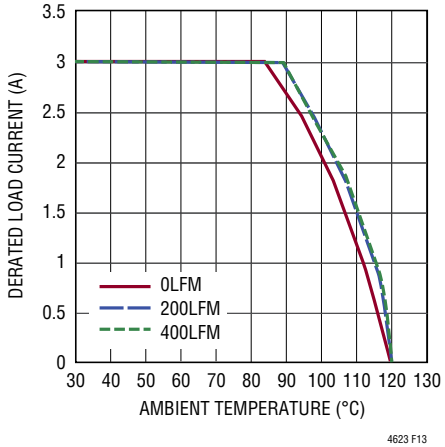


Figure 13. 12V to 1V Derating Curve, No Heat Sink

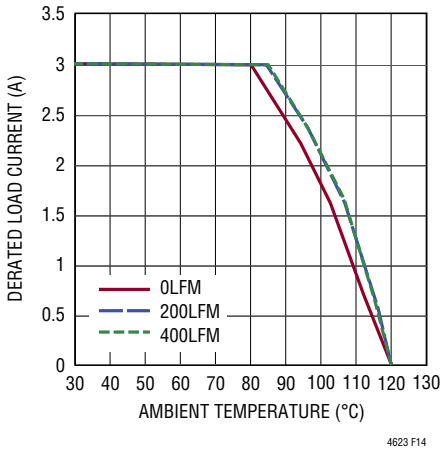


Figure 14. 16V to 1V Derating Curve, No Heat Sink

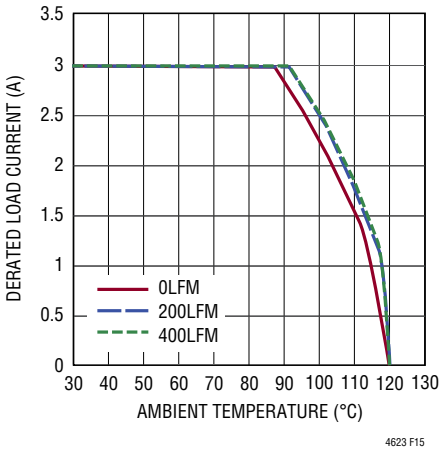


Figure 15. 5V to 1.5V Derating Curve, No Heat Sink

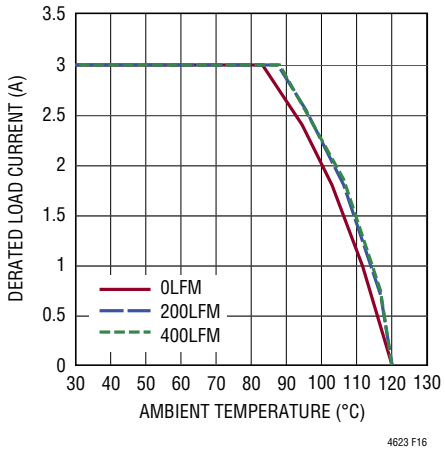


Figure 16. 12V to 1.5V Derating Curve, No Heat Sink

APPLICATIONS INFORMATION

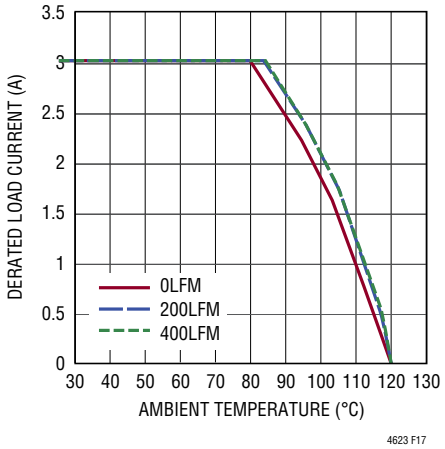


Figure 17. 16V to 1.5V Derating Curve, No Heat Sink

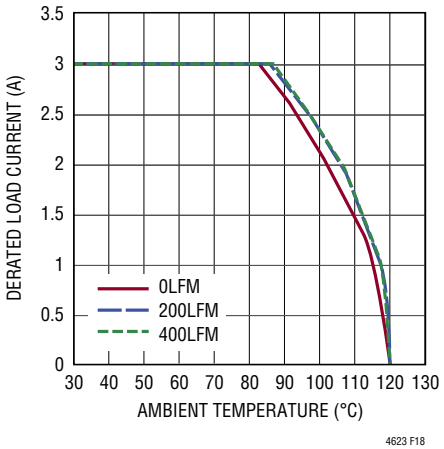


Figure 18. 5V to 3.3V Derating Curve, No Heat Sink

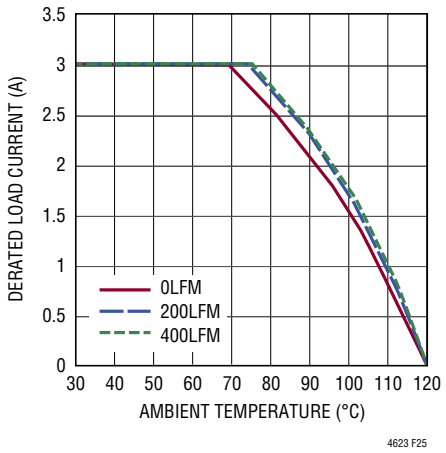


Figure 19. 12V to 3.3V Derating Curve, No Heat Sink

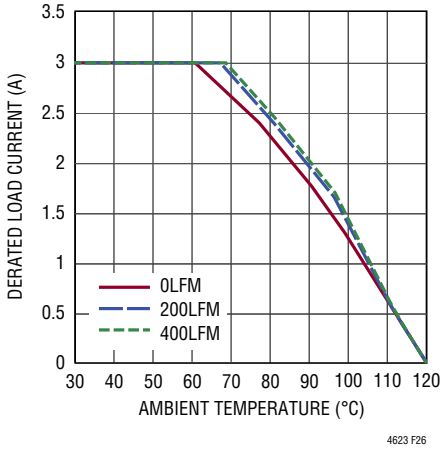


Figure 20. 16V to 3.3V Derating Curve, No Heat Sink

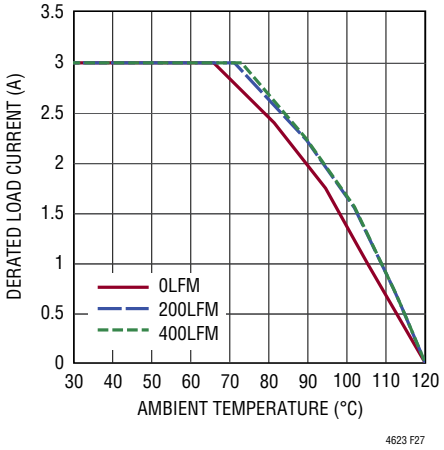


Figure 21. 12V to 5V Derating Curve, No Heat Sink

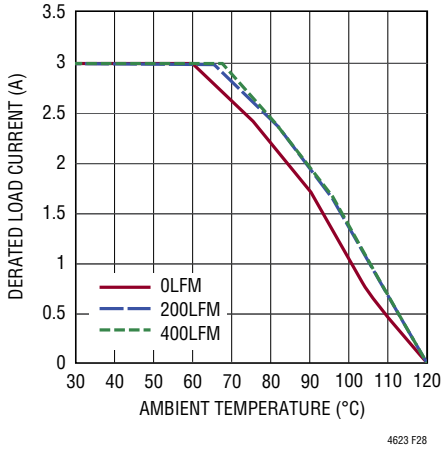


Figure 22. 16V to 5V Derating Curve, No Heat Sink

Table 3. 1.0V Output, No Heat Sink

DERATING CURVE	V_{IN} (V)	POWER LOSS CURVE	AIR FLOW (LFM)	HEAT SINK	$\theta_{JA(°C/W)}$
Figures 12, 13, 14	5, 12, 16	Figure 8	0	None	25
Figures 12, 13, 14	5, 12, 16	Figure 8	200	None	22
Figures 12, 13, 14	5, 12, 16	Figure 8	400	None	22

Table 4. 1.5V Output, No Heat Sink

DERATING CURVE	V_{IN} (V)	POWER LOSS CURVE	AIR FLOW (LFM)	HEAT SINK	$\theta_{JA(°C/W)}$
Figures 15, 16, 17	5, 12, 16	Figure 9	0	None	25
Figures 15, 16, 17	5, 12, 16	Figure 9	200	None	22
Figures 15, 16, 17	5, 12, 16	Figure 9	400	None	22

APPLICATIONS INFORMATION

Table 5. 3.3V Output, No Heat Sink

DERATING CURVE	V_{IN} (V)	POWER LOSS CURVE	AIR FLOW (LFM)	HEAT SINK	$\theta_{JA(°C/W)}$
Figures 18, 19, 20	5, 12, 16	Figure 10	0	None	25
Figures 18, 19, 20	5, 12, 16	Figure 10	200	None	22
Figures 18, 19, 20	5, 12, 16	Figure 10	400	None	22

Table 6. 5V Output, No Heat Sink

DERATING CURVE	V_{IN} (V)	POWER LOSS CURVE	AIR FLOW (LFM)	HEAT SINK	$\theta_{JA(°C/W)}$
Figures 21, 22	12, 16	Figure 11	0	None	25
Figures 21, 22	12, 16	Figure 11	200	None	22
Figures 21, 22	12, 16	Figure 11	400	None	22

Table 7. Output Voltage Response vs Component Matrix (Refer to Figure 24)

C_{IN}	PART NUMBER	VALUE	C_{OUT1}	PART NUMBER	VALUE
Murata	GRM21BR61E106KA73L	10µF, 25V, 0805, X5R	Murata	GRM21BR60J476ME15	47µF, 6.3V, 0805, X5R
Taiyo Yuden	TMK212BBJ106KG-T	10µF, 25V, 0805, X5R	Taiyo Yuden	JMK212BJ476MG-T	47µF, 6.3V, 0805, X5R
Murata	GRM31CR61C226ME15L	22µF, 25V, 1206, X5R			
Taiyo Yuden	TMK316BBJ226ML-T	22µF, 25V, 1206, X5R			

V_{OUT} (V)	C_{IN} (CERAMIC) (µF)	C_{OUT1} (CERAMIC) (µF)	C_{FF} (pF)	V_{IN} (V)	DROOP (mV)	P-P DERIVATION (mV)	RECOVERY TIME (µs)	LOAD STEP (A)	LOAD STEP SLEW RATE (A/µs)	R_{FB} (kΩ)	FREQ (MHz)
1	10	47	100	5, 12	1	59	40	1	1	90.9	1
1.2	10	47	100	5, 12	1	59	40	1	1	60.4	1
1.5	10	47	100	5, 12	1	66	40	1	1	40.2	1
1.8	10	47	100	5, 12	1	75	40	1	1	30.1	1
2.5	10	47	100	5, 12	2	108	50	1	1	19.1	1
3.3	10	47	100	5, 12	3	111	60	1	1	13.3	2
5	10	47	100	12	5	156	60	1	1	8.25k	2

Safety Considerations

The LTM4623 modules do not provide galvanic isolation from V_{IN} to V_{OUT}. There is no internal fuse. If required, a slow blow fuse with a rating twice the maximum input current needs to be provided to protect each unit from catastrophic failure. The device does support thermal shutdown and overcurrent protection.

Layout Checklist/Example

The high integration of LTM4623 makes the PCB board layout very simple and easy. However, to optimize its electrical and thermal performance, some layout considerations are still necessary.

- Use large PCB copper areas for high current paths, including V_{IN}, GND and V_{OUT}. It helps to minimize the PCB conduction loss and thermal stress.
- Place high frequency ceramic input and output capacitors next to the V_{IN}, PGND and V_{OUT} pins to minimize high frequency noise.
- Place a dedicated power ground layer underneath the unit.
- To minimize the via conduction loss and reduce module thermal stress, use multiple vias for interconnection between top layer and other power layers.
- Do not put via directly on the pad, unless they are capped or plated over.

APPLICATIONS INFORMATION

- Use a separated SGND ground copper area for components connected to signal pins. Connect the SGND to GND underneath the unit.
- Bring out test points on the signal pins for monitoring.

Figure 23 gives a good example of the recommended layout.

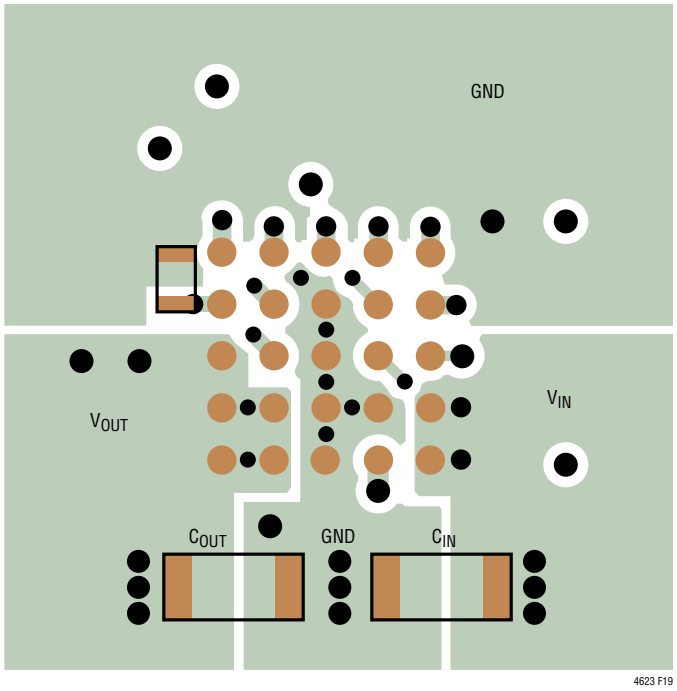


Figure 23. Recommended PCB Layout

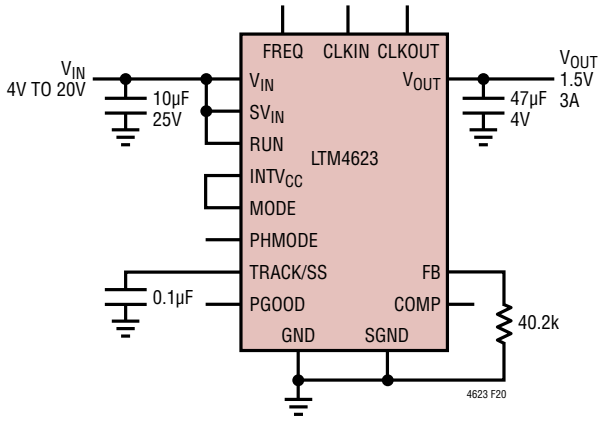


Figure 24. $4V_{IN}$ to $20V_{IN}$, 1.5V Output at 3A Design

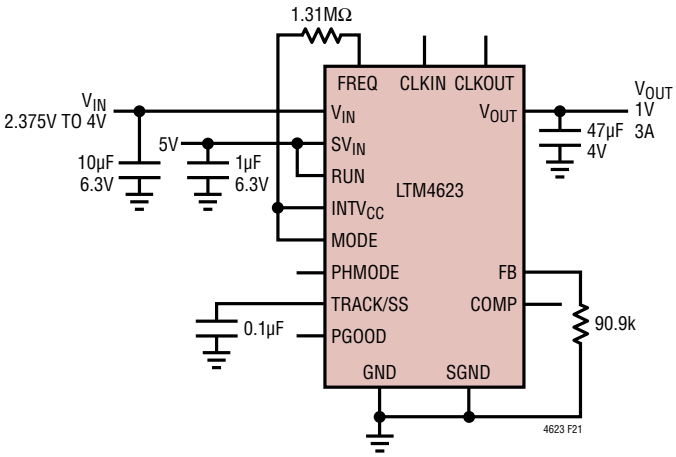


Figure 25. $2.375V_{IN}$ to $4V_{IN}$, 1V Output at 3A Design with 800kHz Reduced Frequency

APPLICATIONS INFORMATION

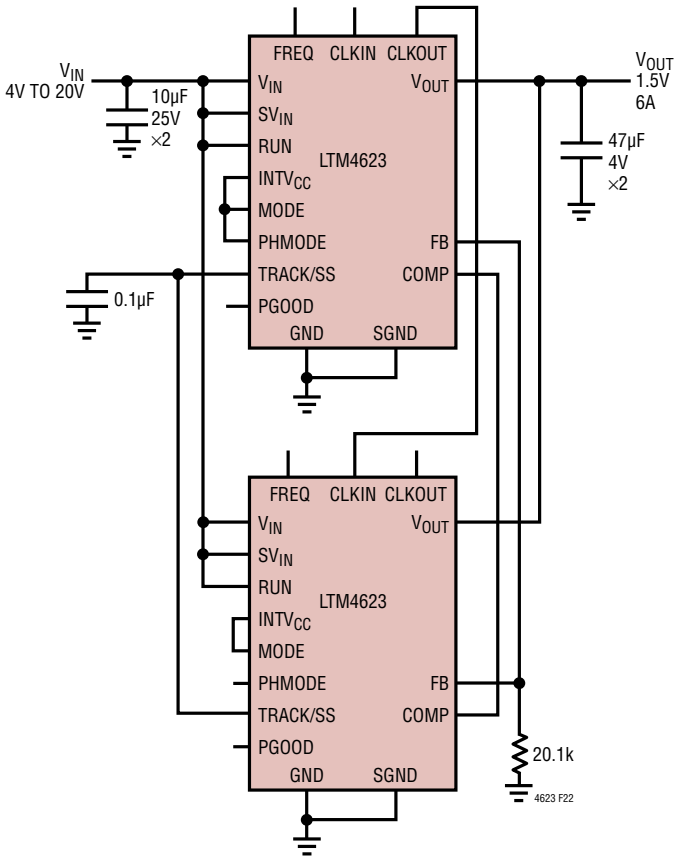


Figure 26. $4V_{IN}$ to $20V_{IN}$, Two Phases, 1.5V at 6A Design

APPLICATIONS INFORMATION

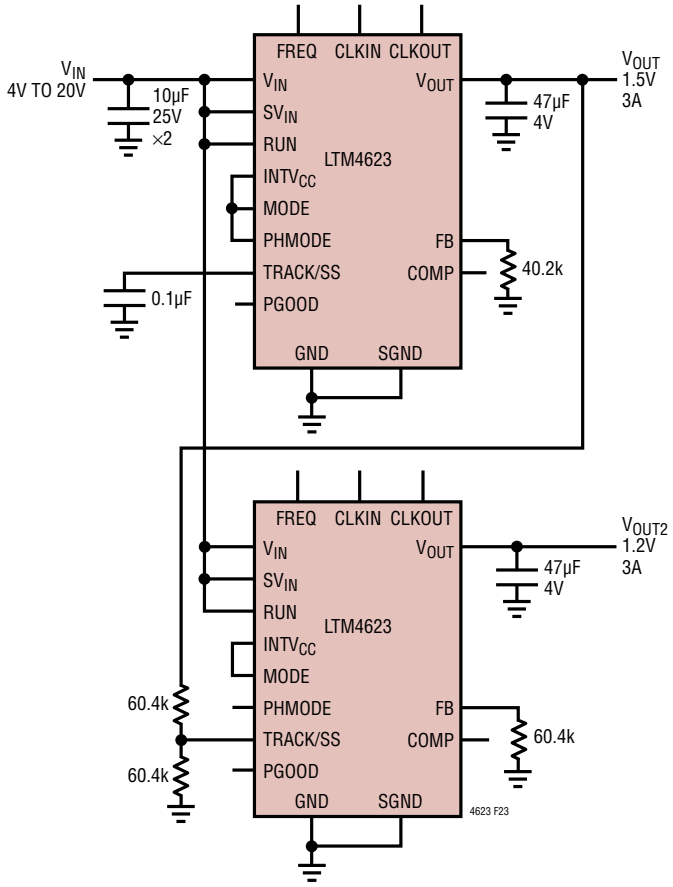


Figure 27. $4V_{IN}$ to $20V_{IN}$, 1.2V and 1.5V with Coincident Tracking

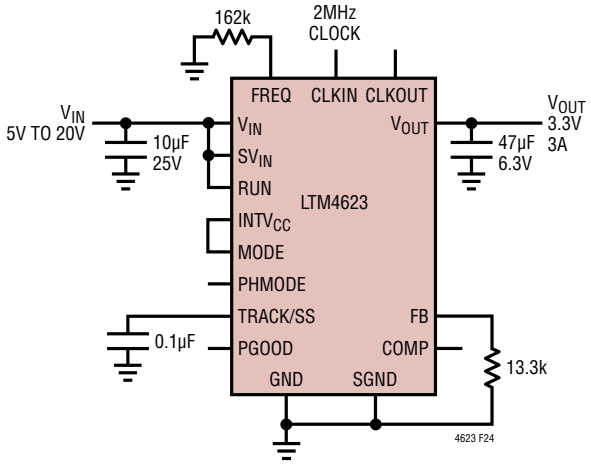


Figure 28. $5V_{IN}$ to $20V_{IN}$, 3.3V Output with 2MHz External Clock

PACKAGE DESCRIPTION

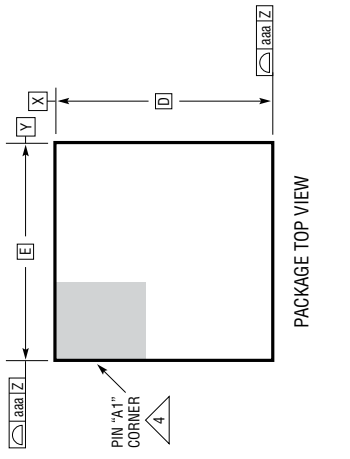
PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY.

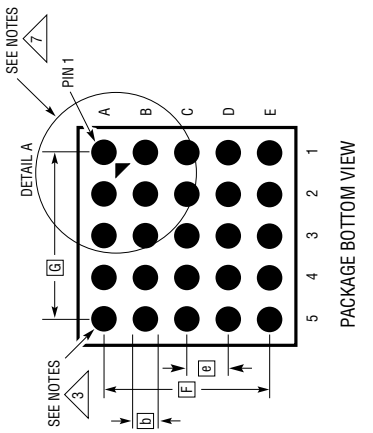
LTM4623 Component LGA and BGA Pinout

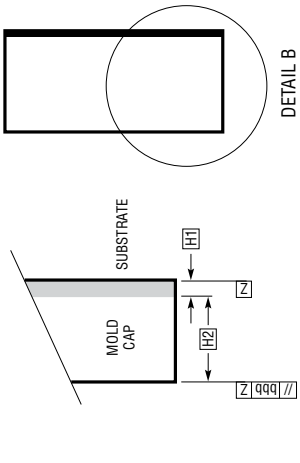
PIN ID	FUNCTION	PIN ID	FUNCTION	PIN ID	FUNCTION	PIN ID	FUNCTION	PIN ID	FUNCTION
A1	COMP	A2	TRACK/SS	A3	RUN	A4	FREQ	A5	CLKIN
B1	FB	B2	PHMODE	B3	GND	B4	SGND	B5	CLKOUT
C1	V_{OUT}	C2	PGOOD	C3	GND	C4	MODE	C5	SV_{IN}
D1	V_{OUT}	D2	V_{OUT}	D3	GND	D4	GND	D5	V_{IN}
E1	V_{OUT}	E2	V_{OUT}	E3	GND	E4	$INTV_{CC}$	E5	V_{IN}

PACKAGE DESCRIPTION

LGA Package
25-Lead (6.25mm × 6.25mm × 1.82mm)
(Reference LTC DWG # 05-08-1949 Rev Ø)



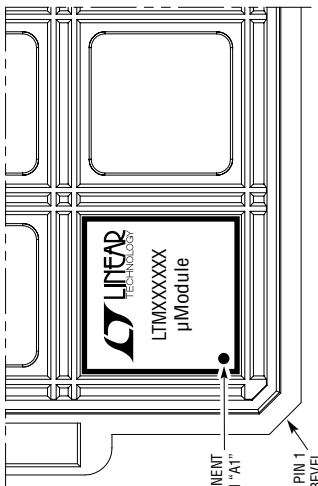


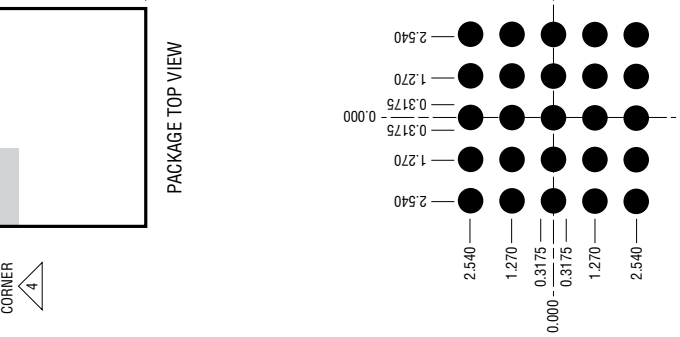


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. LAND DESIGNATION PER JESD MO-222, SPP-010
4. DETAILS OF PAD #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PAD #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. THE TOTAL NUMBER OF PADS: 25
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.72	1.82	1.92	
b	0.60	0.63	0.66	
D		6.25		
E		6.25		
e		1.27		
F		5.08		
G		5.08		
H1	0.27	0.32	0.37	
H2	1.45	1.50	1.55	
aaa			0.15	
bbb			0.10	
eee			0.15	

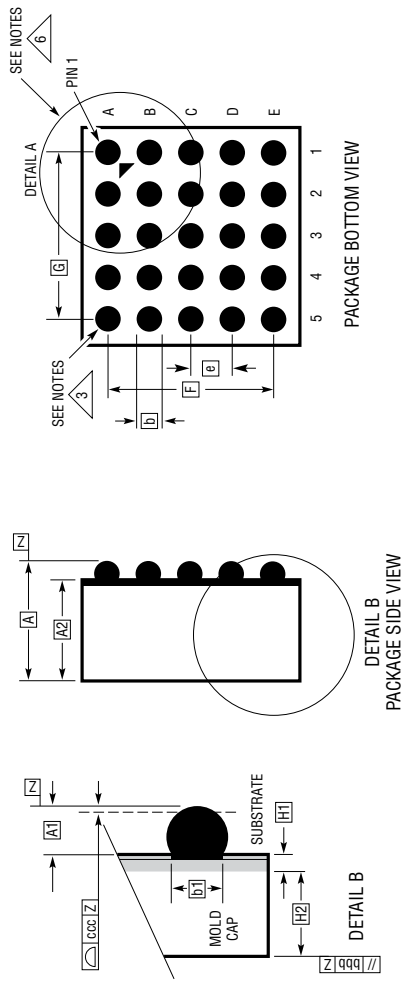
TOTAL NUMBER OF LGA PADS: 25

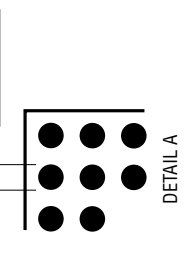




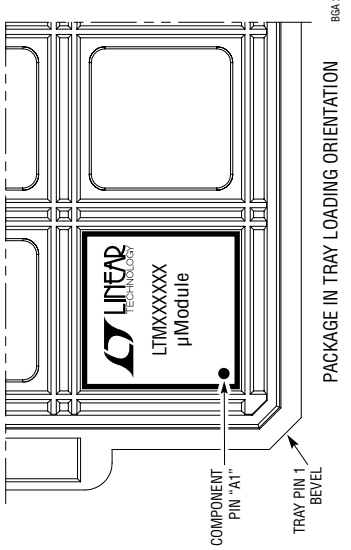
PACKAGE DESCRIPTION

BGA Package
25-Lead (6.25mm × 6.25mm × 2.42mm)
(Reference LTC DWG # 05-08-1502 Rev A)





NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.22	2.42	2.62	
A1	0.50	0.60	0.70	BALL HT
A2	1.72	1.82	1.92	
b	0.60	0.75	0.90	BALL DIMENSION
b1	0.60	0.63	0.66	PAD DIMENSION
D		6.25		
E		6.25		
e		1.27		
F		5.08		
G		5.08		
H1	0.27	0.32	0.37	SUBSTRATE THK
H2	1.45	1.50	1.55	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 25

REVISION HISTORY

REV	DATE	DESCRIPTION	PAGE NUMBER
A	7/15	Corrected R_{FSET} in the Operating Frequency section from 161k to 162k.	10, 22
B	10/15	Added BGA package.	1, 2, 26
C	06/16	Updated Absolute Maximum Ratings section. Peak body temperature from 245°C to 260°C. Added the description about minimum switching frequency in the Operating Frequency section. Changed minimum V_{IN} voltage in Figure 28 from 4V to 5V.	2 11 23
D	07/18	Changed Storage Temperature Range from “–55°C to 125°C” to “–65°C to 150°C”.	2

PACKAGE PHOTOS

DESIGN RESOURCES

SUBJECT	DESCRIPTION	
µModule Design and Manufacturing Resources	Design: • Selector Guides • Demo Boards and Gerber Files • Free Simulation Tools	Manufacturing: • Quick Start Guide • PCB Design, Assembly and Manufacturing Guidelines • Package and Board Level Reliability
µModule Regulator Products Search	1. Sort table of products by parameters and download the result as a spread sheet. 2. Search using the Quick Power Search parametric table. 	
Digital Power System Management	Analog Devices' family of digital power supply management ICs are highly integrated solutions that offer essential functions, including power supply monitoring, supervision, margining and sequencing, and feature EEPROM for storing user configurations and fault logging.	

RELATED PARTS

PART NUMBER	DESCRIPTION	COMMENTS
LTM4625	Higher Current than LTM4623, BGA Package, Taller but Same Footprint	5A, 4V < V_{IN} < 20V_{MAX}
LTM4619	Dual 4A	4.5V < V_{IN} < 28V_{MAX}, 15mm × 15mm × 2.82mm LGA
LTM4644	Quad 4A	Configurable up to 16A, 4V < V_{IN} < 16V_{MAX}, 9mm × 15mm × 5.01mm BGA
LTM4649	10A	4.5V < V_{IN} < 18V_{MAX}, 9mm × 15mm × 4.92mm
LTM8020	200mA, Higher V_{IN} than LTM4625, Same Package Footprint	4V < V_{IN} < 40V_{MAX}, 6.25mm × 6.25mm × 2.32mm LGA

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